Surface Mount Standard Recovery Power Rectifier

SMA Power Surface Mount Package

Features construction with glass passivation. Ideally suited for surface mounted automotive applications.

Features

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Stable, High Temperature, Glass Passivated Junction
- These Devices are Pb-Free and are RoHS Compliant

Mechanical Characteristics

- Case: Molded Epoxy Epoxy meets UL 94 V-0 @ 0.125 in
- Weight: 70 mg (Approximately)
- Finish: All External Surfaces are Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 seconds in Solder Bath
- Polarity: Band in Plastic Body Indicates Cathode Lead
- Marking: MRA4003T3G = R13

MRA4004T3G = R14

MRA4005T1G = R15

MRA4005T3G = R15

MRA4006T3G = R16

MRA4007T3G = R17



ON Semiconductor®

http://onsemi.com

STANDARD RECOVERY RECTIFIERS 1.0 AMPERES 300-1000 VOLTS



CASE 403D SMA

MARKING DIAGRAM



R1x = Specific Device Code

A = Assembly Location

Y = Yeaı

WW = Work Week

= Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the ordering information section on page 4 of this data sheet.

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MAXIMUM RATINGS

		Value					
Rating	Symbol	MRA4003	MRA4004	MRA4005	MRA4006	MRA4007	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	300	400	600	800	1000	Volts
Avg. Rectified Forward Current (At Rated V _R , T _L = 150°C)	I _O	1			Amp		
Peak Repetitive Forward Current (At Rated V _R , Square Wave, 20 kHz, T _L = 150°C)	I _{FRM}	2				Amps	
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions, halfwave, single phase, 60 Hz)	I _{FSM}	30					Amps
Storage/Operating Case Temperature	T _{stg} , T _C	-55 to 150				°C	
Operating Junction Temperature	TJ	-55 to 175				°C	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 1) Thermal Resistance, Junction-to-Ambient (Note 2)	R _{θJL} R _{θJA}	16.2 88.3	°C/W

ELECTRICAL CHARACTERISTICS

		Value		
Characteristic	Symbol	T _J = 25°C	T _J = 100°C	Unit
Maximum Instantaneous Forward Voltage (Note 3) (I _F = 1 A) (I _F = 2 A)	V _F	1.1 1.18	1.04 1.12	Volts
Maximum Instantaneous Reverse Current (at rated DC voltage)	I _R	10	50	μΑ

- 1. Minimum Pad Size
- 2. 1 inch Pad Size
- 3. Pulse Test: Pulse Width \leq 250 μ s, Duty Cycle \leq 2%.

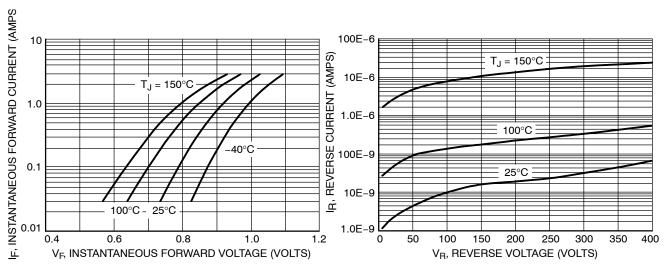


Figure 1. Typical Forward Voltage

Figure 2. Typical Reverse Current

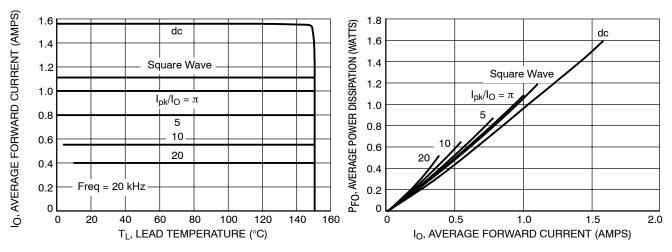


Figure 3. Current Derating per Leg

Figure 4. Forward Power Dissipation per Leg

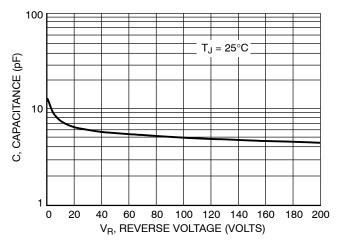


Figure 5. Capacitance

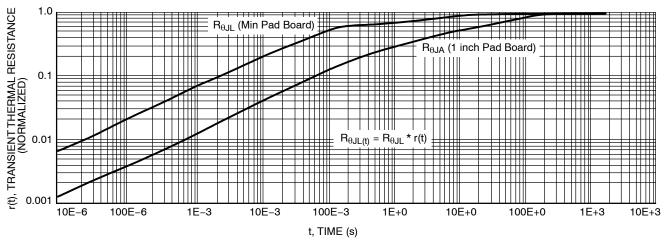


Figure 6. Thermal Response

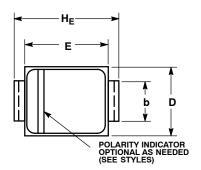
ORDERING INFORMATION

Device	Package	Shipping†
MRA4003T3G	SMA (Pb-Free)	5000/Tape & Reel
MRA4004T3G	SMA (Pb-Free)	5000/Tape & Reel
MRA4005T1G	SMA (Pb-Free)	1500/Tape & Reel
MRA4005T3G	SMA (Pb-Free)	5000/Tape & Reel
MRA4006T3G	SMA (Pb-Free)	5000/Tape & Reel
MRA4007T3G	SMA (Pb-Free)	5000/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

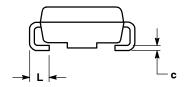
SMA CASE 403D-02 ISSUE F

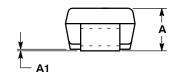


NOTES:

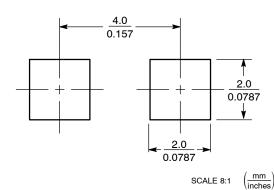
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- 403D-01 OBSOLETE, NEW STANDARD IS 403D-02.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.97	2.10	2.20	0.078	0.083	0.087	
A1	0.05	0.10	0.15	0.002	0.004	0.006	
b	1.27	1.45	1.63	0.050	0.057	0.064	
С	0.15	0.28	0.41	0.006	0.011	0.016	
D	2.29	2.60	2.92	0.090	0.103	0.115	
E	4.06	4.32	4.57	0.160	0.170	0.180	
HE	4.83	5.21	5.59	0.190	0.205	0.220	
L	0.76	1.14	1.52	0.030	0.045	0.060	





SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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